

Active Photonic Routing for Computer Interconnects

- the Prospects for Photonic PCBs

Ian White and Richard Penty

University of Cambridge, Electrical Engineering Division, 9 JJ Thomson Avenue, Cambridge CB3 0FA, United Kingdom

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> Centre for Advanced Photonics and Electronics EPSRC, Cambridge Integrated Knowledge Centre





Next Gen IBM Supercomputer -

Interconnect costs: \$625M (\$25/Gb/s)

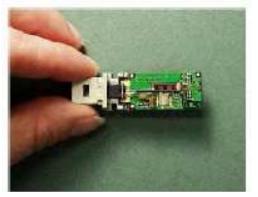
Targeted Interconnect costs: \$25M (at \$1/Gb/s)

- Image: Non-State StateSimulator
 - Computer performance is a function of internal architecture, processor speed, external architecture, data and I/O access ...
 - Cluster architectures provide value and require lots of interconnect
 - now the most common architecture for top 500 machine

http://www.top500.org/lists/2005/06/PerformanceDevelopment.php

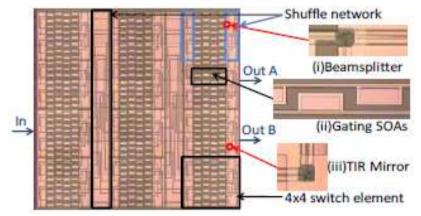


Interconnect and Routing Options for Computer Networks Modular Integration Sub-systems

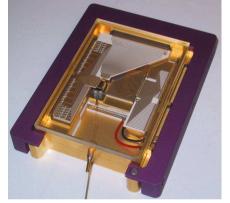


Source:

LA Buckman et al., IEEE PTL, Vol.14, pp 702-704, 2002



University of Cambridge, 2009



Infinera, OFC 2005





Luxtera Products



High speed aptical modulator realized in CMOS-SOL



Is there another way?

Waveguides (and components) on the PCB?

- Optical Interconnects today
 - We buy modules
- Electrical Interconnects today
 - Mostly assembled from subcomponents very cheap!
- Can we move Optics to mass manufacturing from sub-components?
 - Polymer waveguides on PCB?



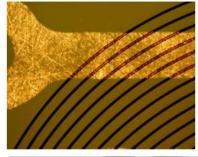
Siloxane Polymer PCBs

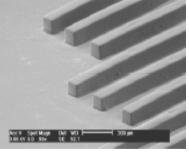
Siloxane materials engineered exhibiting suitable mechanical, thermal and optical properties (OE4140 and OE4141):

- are flexible for use with PCBs (suitable for printing!)
- exhibit high processability
 - exhibiting high thermal and environmental stability: withstand > 350 °C
 - \rightarrow can be integrated with PCBs
- Low reported loss:
 - ~ 0.05 dB/cm @ 850 nm
 - ~0.006 dB/crossing using SMF launch
- Excellent crosstalk performance:
 - < -60 dB in intersecting waveguide
- High speed > 10 Gb/s operation







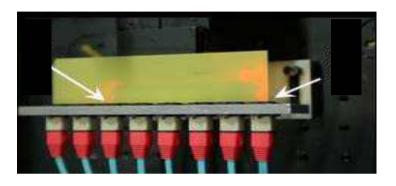


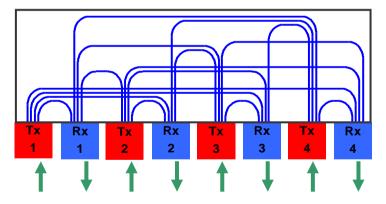
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Polymer Optical Backplane Architecture





Requirements:

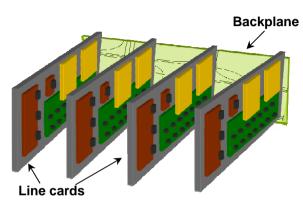
passive routing scalable architecture low loss and crosstalk

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Ribbon fibres connect at board edges and run to line cards

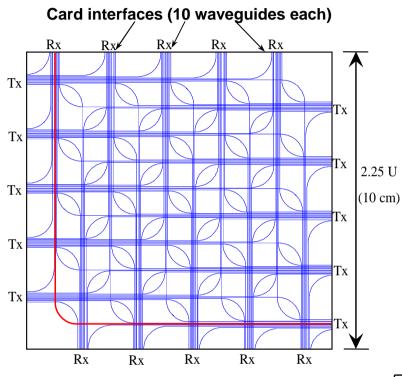
Standard ribbon fibre link backplane to transmit and receive arrays mounted on line-cards



Schematic of conventional electrical backplane with pluggable line cards



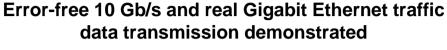
Demonstrated 10 Card Optical Backplane

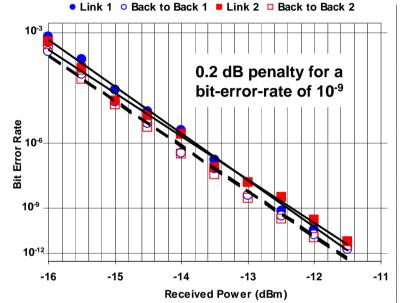


Schematic of 10-card backplane layout

- 100 waveguides
- single 90° bend per waveguide
- 90 crossings or less per waveguide

Terabit capacity enabled by 100 waveguides each capable of 10 Gb/s operating in multicast mode



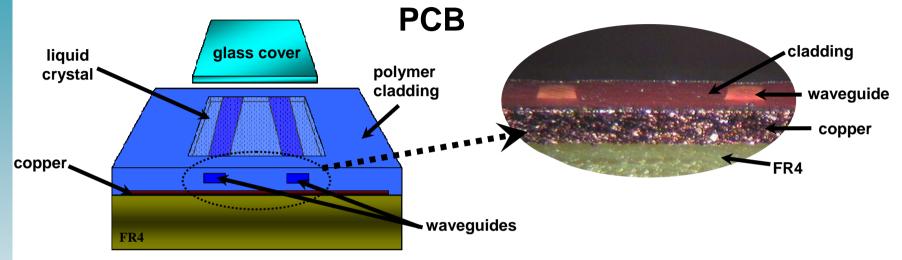


Input Type	Insertion Loss	Worst-case Crosstalk
50 μm MMF	2 to 8 dB	< -35 dB
SMF	1 to 4 dB	< -45 dB

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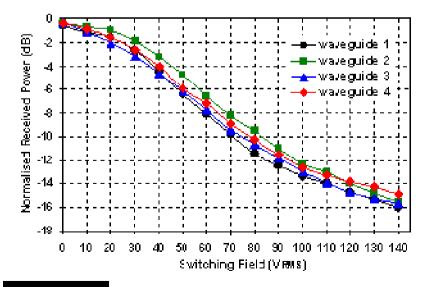


Active Routing: Integrated LC/polymer Switch on FR4



- Mixture of two nematic liquid crystals: Merck ZLI-1840 and 1550
- Bulk planar alignment of the liquid-crystal parallel to the waveguides using a rubbed polyimide layer on the underside of the ITO top contact
- 850 nm operating λ (though easily varied)
- 0.5 dB excess loss and 15 dB switching
- Excellent repeatability ~0.5 dB across 4 waveguides

Ack T Wilkinson, S Morris, O Hadeler Cambridge University



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Final Comments

- Photonics in period of transition with enormous potential for new low cost high performance user-designed optical systems
- Polymer siloxane materials satisfy necessary requirements for low-cost and large-scale integration of *waveguides and active and passive components* into PCBs

Points for Discussion:

- 1. Are Printed Electro-optical PCBs a promising technology for use in high-speed short-reach optical interconnection applications where light is retained in the PCB?
- 2. Are there opportunities for integrated active polymer (laser/modulator/detector) components?

